ace of Form PTO-1595

01 FC:581

07-10-2001

Docket No.

10 01

10-	1771100
To the Assistant Commissione 10°	1//1493 the attached original
1. Name of conveying party(ies):	<pre>2. Name and address of receiving party(ies):</pre>
Seiichi Iwamatsu	SI Diamond Technology, Inc. 3006 Longhorn Blvd., Suite 107 Austin, Texas 78758
3. Nature of conveyance:	
X Assignment	
Execution Date: May 16, 2001	
4. Application number(s) or patent numb	per(s):
If this document is being filed toge execution date of the application is	ether with a new application, the
A. Patent Application No.(s) 09/836,857	B. Patent
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Kelly K. Kordzik Winstead Sechrest & Minick P.C. 5400 Renaissance Tower 1201 Elm Street Dallas, TX 75270	7. Total fee (37 CFR 3.41) \$ 40.00 Authorized to be charged to deposit account X Check enclosed
(512) 370-2851 DBYRNE 00000120 09836857	8. Deposit account number:
40.00 OP DO NOT U	JSE THIS SPACE
9. Statement and signature. To the best of my knowledge and belacorrect and any attached copy is a Kelly K. Kordzik	ef, the foregoing information is true and true copy of the original document.
	ignature Date
Total (number of pages including cover sheet: 2

PATENT REEL: 011948 FRAME: 0466

ASSIGNMENT

Whereas, I,

(1) Seiichi Iwamatsu,

of 10-58 Naka Ohshio Chino, Nagano 391-0215 Japan

have invented certain improvements in

ELECTRON BEAM DUPLICATION LITHOGRAPHY METHOD AND APPARATUS

and executed, respectively, a United States patent application therefor on (Dates Inventors Signed Declaration) (1) Man 16, 2001.

Whereas, SI DIAMOND TECHNOLOGY, INC., a corporation of Texas, having a place of business at 3006 Longhorn Blvd., Suite 107, Austin, Texas 78758 (hereinafter called SIDT), desires to acquire the entire right, title and interest in the said application and inventions, and to any United States and foreign patents to be obtained therefor;

Now, therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to SIDT, its successors and assigns, the entire right, title and interest in the said application and inventions therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to SIDT, its successors and assigns; and we hereby agree that SIDT may apply for foreign Letters Patent on said inventions and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by SIDT.

(1) Signed at <u>Japan</u>, on <u>May 16</u>, 2001.

Seiichi Iwamatsu

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RECORDED: 07/02/2001

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PATENT REEL: 011948 FRAME: 0467